

Résiste® 165 E



Label Facestock



Key Features

- Made with our industry-leading, patent-pending, phenol-free direct thermal chemistry
 - Unmatched resistance to fading
 - Aquatic-friendly
- Lower energy required to print high-contrast images
- Improved resistance to heat, water, and alcohol
- Imaging speed up to 8 ips
- Repulpable

Applications

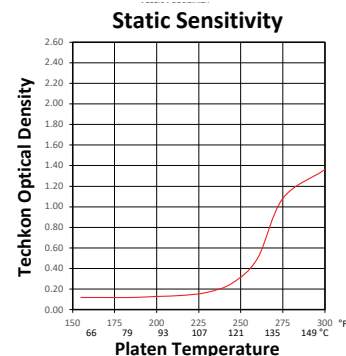
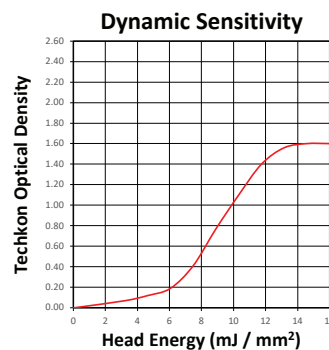
- Package Delivery Labels
- Logistics Labels



Résiste® 165 E is a topcoated direct thermal label facestock that was specifically designed with our patent-pending phenol-free direct thermal chemistry to revolutionize package delivery and logistics direct thermal label production with enhanced end-user performance and value.

Product Characteristics – Provisional Data

Caliper	3.0 +/- 0.2 mils 76.2 +/- 5 µm
Basis Weight	17 x 22–500 (lbs) g/m2
Thermal Response - Nominal	
Static (°C ± 5°)	
Initial Activation Temperature 0.2 ODU	113° C, 236° F
1.0 ODU	133° C, 272° F
Maximum Density (ODU)	1.36
Temperature Required	148° C
Dynamic—Atlantek 400 (mj/mm2)	
Initial Printer Energy 0.2 ODU	6.1
1.0 ODU	9.7
Maximum Density (ODU)	1.6
Energy Required	16.0
Brightness (UV Excluded)	86.92
Gurley Stiffness Nominal (mg)	MD 90 CD 35
Elmendorf Tear Nominal (g)	MD 45 CD 45
Tensile (lbs/in)	MD 37 CD 17
Parker Print Surface	1.15



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